



Layer	Stack up	Supplier	Supplier Description	Description	Type	Base Thickness	Processed Thickness	Resin Content	εr	Mask Thickness	
1		Coates	LPI	Solder resist	Solder resist		0.020		4.100	0.020	
			12um Copper Foil	Foil	Foil	0.012	0.037				
2		VENTEC	VT47-1080 - RC66%	VT47-1080 - RC66%	PREPREG	0.086	0.077	66.000	3.950		
			12um Copper Foil	Foil	Foil	0.012	0.037				
3		VENTEC	VT47-1080 - RC66%	VT47-1080 - RC66%	PREPREG	0.086	0.077	66.000	3.950		
							0.017	0.017			
4		VENTEC	1.000mm	VT-47	Core	0.991	0.991	0.000	4.400		
							0.017	0.017			
5		VENTEC	VT47-1080 - RC66%	VT47-1080 - RC66%	PREPREG	0.086	0.077	66.000	3.950		
			12um Copper Foil	Foil	Foil	0.012	0.037				
6		VENTEC	VT47-1080 - RC66%	VT47-1080 - RC66%	PREPREG	0.086	0.077	66.000	3.950		
			12um Copper Foil	Foil	Foil	0.012	0.037				
		Coates	LPI	Solder resist	Solder resist		0.020		4.100	0.020	

Copper Thickness = 0.182 | Dielectric Thickness = 1.301 | Solder Mask Thickness = 0.040 |
Stack Up Thickness = 1.483 | Stack Up Thickness with Soldermask = 1.523

Structure Image	Impedance ID	Structure Name	Impedance Signal Layer	Ref. Plane 1 in Layer	Ref. Plane 2 in Layer	Lower Trace Width (W1)	Trace Separation (S1)	Ground Strip Separation (D1)	Calculated Impedance	Target Impedance	Tol (+/- %)	CI Notes-1
	1	Edge Coupled Coated Microstrip 1B	1	2	0	0.100	0.180	0.000	100.100	100.000	10.000	
	2	Edge Coupled Coated Microstrip 1B	1	2	0	0.120	0.150	0.000	90.130	90.000	10.000	
	3	Edge Coupled Offset Stripline 1B1A	3	2	4	0.100	0.200	0.000	95.680	100.000	10.000	
	4	Edge Coupled Offset Stripline 1B1A	3	2	4	0.120	0.180	0.000	86.870	90.000	10.000	
	5	Edge Coupled Offset Stripline 1B1A	4	3	5	0.100	0.200	0.000	95.680	100.000	10.000	
	6	Edge Coupled Offset Stripline 1B1A	4	3	5	0.120	0.180	0.000	86.870	90.000	10.000	
	7	Edge Coupled Coated Microstrip 1B	6	5	0	0.100	0.180	0.000	100.100	100.000	10.000	





StackName: NCI_PCB4405A_6L_mvt_VT47	Version:	Revision:	Modification:	Date of Revision:	Editor	Page 1/2	
Date: 11/9/2023	Associated Documents:						
Author: Mostefa Abdali							
Department: IDS							
Site: Tewkesbury							




Structure Image	Impedance ID	Structure Name	Impedance Signal Layer	Ref. Plane 1 in Layer	Ref. Plane 2 in Layer	Lower Trace Width (W1)	Trace Separation (S1)	Ground Strip Separation (D1)	Calculated Impedance	Target Impedance	Tol (+/- %)	CI Notes-1	
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	8	Edge Coupled Coated Microstrip 1B	6	5	0	0.120	0.150	0.000	90.130	90.000	10.000		
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Drill Image	1st Layer	2nd Layer	Column Position	Drill Type	Minimum Drill Size	Minimum Size	Minimum Pad Size	Fill Type	Data Filenames	
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	1	6	1	Mechanical PTH	0.000	0.250	0.000	None		
	2	3	5	Laser PTH	0.000	0.125	0.250	None	dummy drill	
	5	4	3	Laser PTH	0.000	0.125	0.250	Copper Fill		
	6	5	3	Laser PTH	0.000	0.125	0.250	Copper Fill		

Notes

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